



## LEAD FREE ALLOY

### Sn99 CuSP

**Sn99 CuSP LEAD FREE ALLOY** – Eutectic alloy for soldering printed circuits, produced from very high quality metals Eutectic alloy for soldering of printed circuit boards and components, produced from very high quality metals.

This alloy was specially developed with the special addition of alloy components designed to reduce oxide production and to increase the fluidity of the molten solder.

Suitable for Hot Air Solder Levelling and Wave Soldering processes.

#### Chemical Characteristics

Amount of Tin:	99.3% +/- 0.2%
Amount of Copper:	0.7% +/- 0.2%
Tin for first melting:	>99.98%.
Copper purity:	>99.99%

#### Physical Characteristics, standard:

Melting point	227°C Eutectic.
Specific weight	7.3
Working temperature	250 to 280°C ( <i>wave soldering</i> )

Maximum content of impurities: see below:

Cd	Sb	Bi
<0.002%	<0.05%	<0.01%

Fe	Zn	Al	As
<0.02%	<0.001%	<0.001%	<0.01%

Pb	Other
<0.05%	<0.05%

#### Supplied as:

Bars	Extruded bars or sticks in cartons of 20 Kg ( Exact Tare weight stated on carton).
Wire	On spools of 15 Kgs. (others please contact us)
Powder	In metallic buckets of 25 Kg
Quality Insurance	Certificates of conformity can be supplied with each lot if required.
Labelling	Cartons/containers labels show manufactured batch number and alloy.

#### Storage:

- Original packaging at an average temperature of 20°C